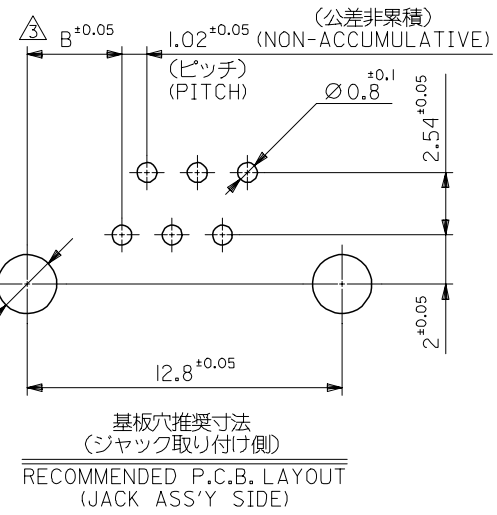


注記
NOTES

- 材質
MATERIAL
ハウジング: ガラス入りポリエステル UL 94V-0 (色: グレイ)
UL 94V-0 (色: グレイ)
HOUSING: POLYESTER G.F.15% UL94V-0 (COLOR:GRAY)
- ターミナル: リン青銅 (t=0.38)
TERMINAL: PHOSPHOR BRONZE (t=0.38)
- 金属ペグ: リン青銅、錫メッキ (t=0.4)
METAL PEG: PHOSPHOR BRONZE (t=0.4), PRE-TINNED
- ターミナルのメッキ仕様
PLATING OF TERMINAL
接点部: 金メッキ、表参照
CONTACT AREA: GOLD PER TABLE
- 半田付け部: 錫メッキ 1.0 μmMIN.
SOLDER AREA: TIN 1.0 μmMIN.
- 下地メッキ: ニッケルメッキ 1.0 μmMIN.
UNDERPLATE: NICKEL 1.0 μmMIN.

- △3 -64*2は、両端の基板穴を除く。
-62*2は、両端2つの基板穴を除く。
DIM. "B" INDICATES FIRST P.C. HOLE REQUIRED PER PART NUMBER. FOR PARTIALLY LOADED ASSEMBLIES P.C. HOLE PATTERN IS REDUCED FROM EACH END.
- △4 金メッキ厚標示
COLOR CODING TO INDICATE GOLD PLATING
黄色: 0.1 μmMIN.
YELLOW: 0.1 μmMIN.
緑色: 0.38 μmMIN.
GREEN: 0.38 μmMIN.
オレンジ色: 0.76 μmMIN.
ORANGE: 0.76 μmMIN.
無色: 1.27 μmMIN.
UNMARKED: 1.27 μmMIN.
- 推奨基板厚: t=1.6±0.05
RECOMMENDED P.C.B. THICKNESS: 1.6±0.05
- 本製品は52830-6**5の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 52830-6**5.



6	6	3.85	5.08	1.27	52830-6642
				0.76	-6632
6	4	4.87	3.05	0.38	-6622
				0.1	-6612
				1.27	-6442
6	2	5.89	1.02	0.76	-6432
				0.38	-6422
				0.1	-6412
6	2	5.89	1.02	1.27	-6242
				0.76	-6232
				0.38	-6222
				0.1	52830-6212
POSITION	CIRCUIT	B	(A)	金メッキ厚 (μmMIN.) Au PLATING THK. (μmMIN.)	MATERIAL NO.

REVISED EC NO: J2006-0419 DRW: HVAJIMA 2005/11/02 CHK: DAN, UKITA 2005/11/07 APPR: NUKITA 2005/11/10	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY Y. SAKIYAMA	DATE '04/04/20	TITLE BOTTOM LATCH MODULAR JACK HOUSING ASS'Y -LEAD FREE-	
	10 OVER 30 UNDER	±0.25	CHECKED BY M. SASAO	DATE '04/04/20	MOLEX INCORPORATED	
	30 OVER	±0.3	APPROVED BY M. SASAO	DATE '04/04/20	DOCUMENT NO. SD-52830-002	SHEET NO. 1 OF 1
A	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		